
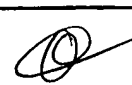
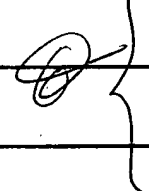



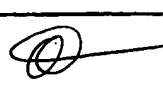
INFORMATION DISCLOSURE CITATION IN AN APPLICATION				ATTY. DOCKET NO. 49657-217		SERIAL NO.	
(PTO-1449)				APPLICANT Shigeki OHBAYASHI			
				FILING DATE November 20, 1998		GROUP 2133	



U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,703,510	Dec. 30, 1997	Iketani et al. — <i>Duplicate</i>			

FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	06-069425	March 11, 1994	Japan (with English abstract)	<i>Duplicate</i>			
	06-005069	Jan. 14, 1994	Japan (with English abstract)				
	02-302987	Dec. 14, 1990	Japan (with English abstract)				

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	JEDEC Standard No. 21-C, JEDEC, December 22, 1994, pp. 3.7.8-7 — <i>Duplicate</i>
	"BGA Packages, Gaining Popularity in U.S.; Make High Density Mounting of High Pin Count LSIs Easy", A. Fukuda, Nikkei Electronics, Feb. 14, 1994, pp. 59-73.
	M5M5V1132FP, GP-6, -7, -8, -7L, -8L, Mitsubishi's Product Data Sheet March 24, 1997, pp. 1-14. — <i>Duplicate</i>

EXAMINER 	DATE CONSIDERED 8/16/05
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.